

UHF linear power transistor

BLV59

FEATURES

- Internal input matching to achieve an optimum wideband capability and high power gain
- Emitter-ballasting resistors for lower junction temperatures
- Titanium-platinum-gold metallization ensures long life and excellent reliability.

APPLICATIONS

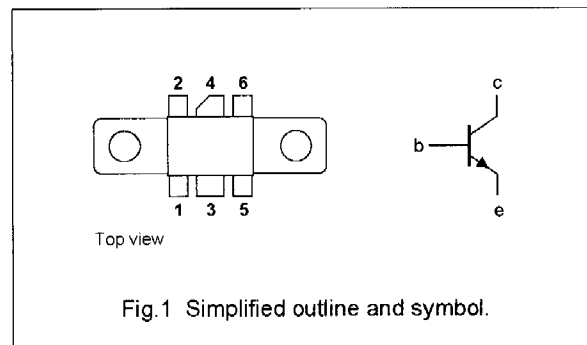
- UHF linear amplifiers in television transmitters.

DESCRIPTION

NPN silicon planar epitaxial power transistor encapsulated in a 6-lead SOT171A flange package with a ceramic cap. All leads are isolated from the flange.

PINNING - SOT171A

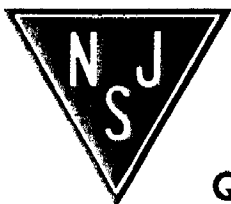
PIN	SYMBOL	DESCRIPTION
1	e	emitter
2	e	emitter
3	b	base
4	c	collector
5	e	emitter
6	e	emitter



QUICK REFERENCE DATA

RF performance at $T_h = 25^\circ\text{C}$ in a common emitter class-AB circuit.

MODE OF OPERATION	f (MHz)	V_{CE} (V)	P_L (W)	G_p (dB)	η_c (%)
CW, class-AB	860	25	30	>7	>50



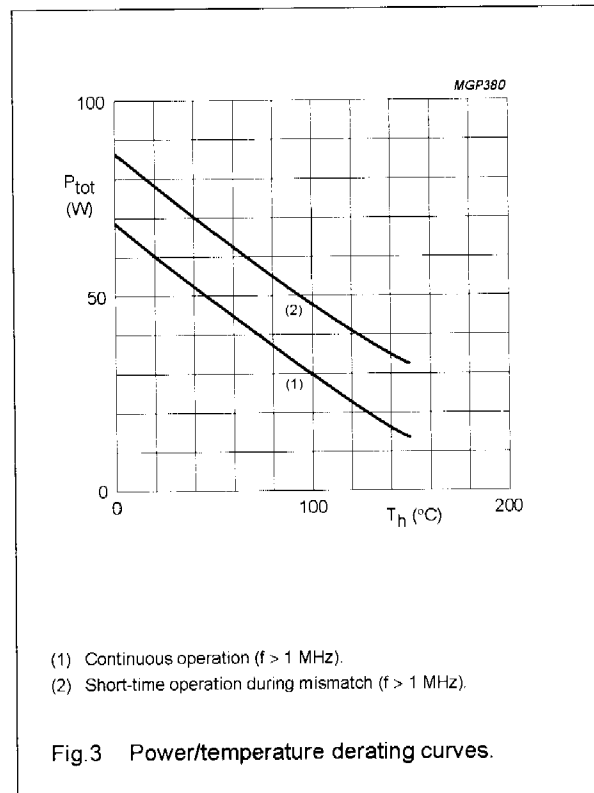
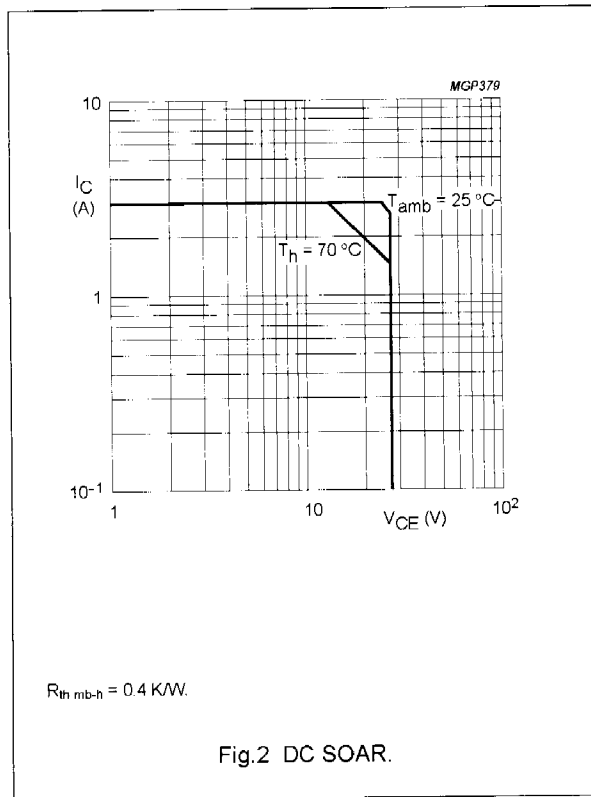
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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	50	V
V_{CEO}	collector-emitter voltage	open base	–	27	V
V_{EBO}	emitter-base voltage	open collector	–	3.5	V
I_C	collector current (DC)		–	3	A
$I_{C(AV)}$	average collector current		–	3	A
I_{CM}	peak collector current	$f > 1 \text{ MHz}$	–	9	A
P_{tot}	total power dissipation	$T_{mb} = 25 \text{ }^\circ\text{C}; f > 1 \text{ MHz}$	–	70	W
T_{stg}	storage temperature		–65	+150	$^\circ\text{C}$
T_J	operating junction temperature		–	200	$^\circ\text{C}$



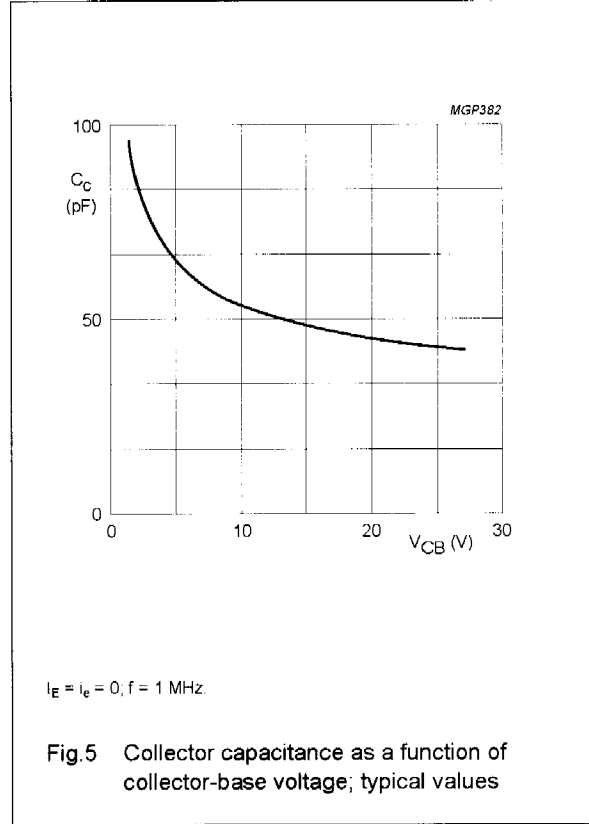
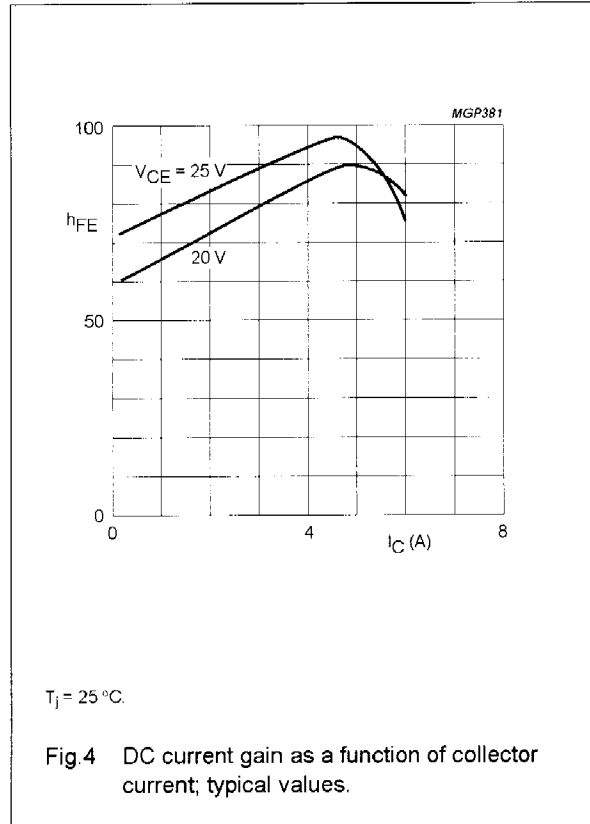
THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-mb}$	thermal resistance from junction to mounting base	$T_{mb} = 25\ ^\circ\text{C}, P_{tot} = 50\ \text{W}$	2.3	K/W
$R_{th\ mb-h}$	thermal resistance from mounting base to heatsink		0.4	K/W

CHARACTERISTICS

$T_j = 25\ ^\circ\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)CBO}$	collector-base breakdown voltage	open emitter; $I_C = 50\ \text{mA}$	50	–	–	V
$V_{(BR)CEO}$	collector-emitter breakdown voltage	open base; $I_C = 100\ \text{mA}$	27	–	–	V
$V_{(BR)EBO}$	emitter-base breakdown voltage	open collector; $I_E = 10\ \text{mA}$	3.5	–	–	V
I_{CES}	collector leakage current	$V_{CE} = 27\ \text{V}, V_{BE} = 0$	–	–	10	mA
$E_{(SBR)}$	second breakdown energy	$L = 25\ \text{mH}; f = 50\ \text{Hz}; R_{BE} = 10\ \Omega$	4	–	–	mJ
h_{FE}	DC current gain	$V_{CE} = 24\ \text{V}; I_C = 2\ \text{A}$	15	–	–	
C_c	collector capacitance	$V_{CB} = 25\ \text{V}; I_E = i_e = 0; f = 1\ \text{MHz}$	–	44	–	pF
C_{re}	feedback capacitance	$V_{CE} = 25\ \text{V}; I_C = 0; f = 1\ \text{MHz}$	–	30	–	pF
C_{cf}	collector-flange capacitance		–	2	–	pF



PACKAGE OUTLINE

Flanged ceramic package; 2 mounting holes; 6 leads

SOT171A

